Product Change Notification

Change Notification #: 116176 - 01

Change Title: Select Intel® Optane™ Memory Series,
PCN 116176-01,
Transport Media, Product Design,
Clamshell Packaging Change and Adding
Alternative Printed Board Assembly (PBA)
Reason for Revision: Modify item 2 in the "Description of Change to Customer" with 3 more alternates and update Future clamshell packaging images

Date of Publication: September 18, 2018

Key Characteristics of the Change:

Transport Media, Product Design,

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	May 03, 2018

Description of Change to the Customer:

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Select Intel® Optane™ Memory Series SKUs will undergo the following two changes:

1) A package design change to improve scalability and flexibility to support multiple products in the same new clamshell. The new clamshell design is 100% recyclable and ESD safe. See details and pictures below.

CURRENTLY: Existing Package, based on form factor, requires unique packaging solution.

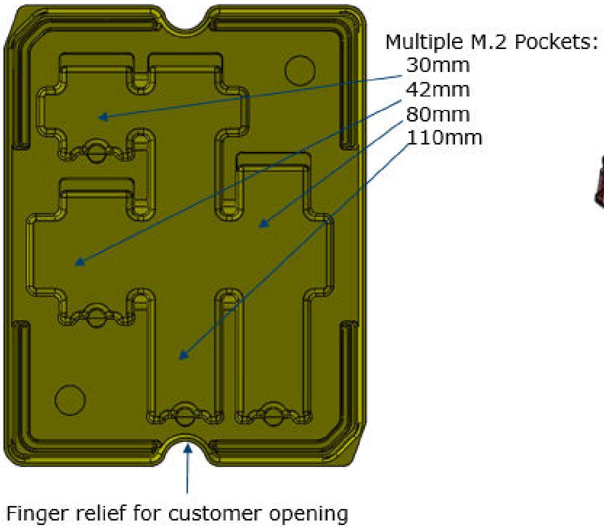
Individual Clamshell
Different clamshells required for each form factor

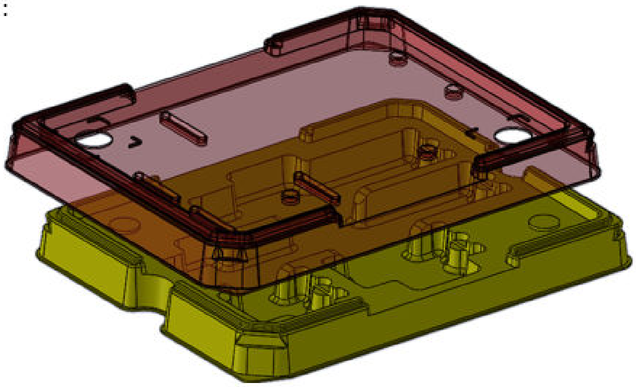
Corrugated Insert
Different corrugated inserts required for each form factor

White Box
Common box across 30mm, 42mm ad 80mm drives. 110mm requires custom white box

Labelled and sealed

FUTURE: MOQ1 clamshell with common Base and cover





Common base and cover - 2230, 2242, 2280, 22110

Dimension - 140mmX110mmX16.5mm

Design allows for M.2 drives with or without heat spreaders

M.2 MOQ1 Packaging

Packaging label (MOQ1 only)

Example (80 mm drive):

2) To improve supply availability, Intel is adding an alternative Power Management Integrated Circuit (PMIC), an alternative Print Circuit Board(PCB) and an alternative FET, an alternative SPI NAND FLASH to the products listed in the Products Affected/Intel Ordering Codes Table.

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers as a result of these changes. The changes to the products do not affect form, fit or functionality and the alternative PBA number is not changing. Additionally, the alternative PBA has met all Intel requirements & passed the same set of internal qualifications.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® Optane™ Memory Series, Single Pack	MEMPEK1J016GA01	960260
Intel® Optane™ Memory Series, Single Pack	MEMPEK1J032GA01	960261
Intel® Optane™ Memory Series, 100 Pack	MEMPEK1J016GA	960268
Intel® Optane™ Memory Series, 100 Pack	MEMPEK1J032GA	960270

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
April 03, 2018	00	Originally Published PCN
September 18, 2018	01	Modify item 2 in the "Description of Change to Customer" with 3 more alternates and update Future clamshell packaging images

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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